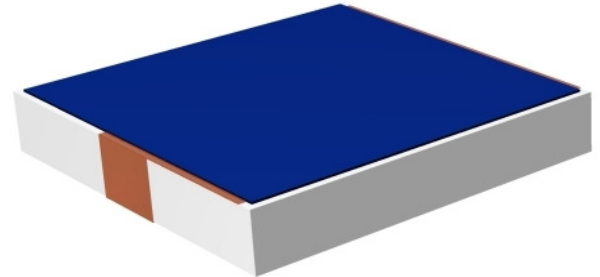


## FEATURES

- Low Profile Surface Mount
- High Power
- Aluminum Nitride Substrate
- Low VSWR
- Ideal For Automated Assembly

## APPLICATIONS

- Mobile Networks
- Broadcast
- High Power Amplifiers
- Instrumentation
- Isolators
- Military
- Satellite Communications



## GENERAL DESCRIPTION

EMC Technology's surface mount terminations are designed for direct installation on printed circuit boards and manufactured using thick film technology. Edge metallization on two sides forms the solder fillets for stronger attachment, easier inspection, and increased heat removal area. The devices are available in Alumina, Aluminum Nitride or Beryllium Oxide.

## SPECIFICATIONS

### 1.0 ELECTRICAL

Nominal Impedance:	50 Ω
Frequency Range:	DC – 4.0 GHz
VSWR:	DC 2.7 GHz 1.13:1 Max 2.7 – 4.0 GHz 1.20:1 MAX
Temperature Coefficient:	±200 PPM/°C Max
Power Rating:	150 Watts
Operating Temperature:	-55 °C To +200 °C
DC Resistance:	50 Ω ± 2%

### 2.0 MECHANICAL

Substrate:	Aluminum Nitride
Resistive Film:	Thick Film
Metallization:	Thick Film, Silver Plated

### 3.0 UNIT MARKING

None

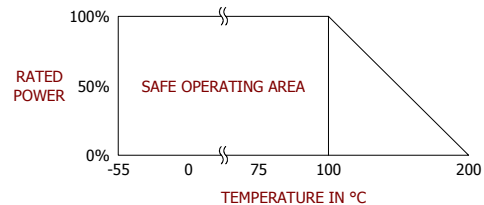
### 4.0 PACKAGING

Standard:	Tape and Reel
Optional:	Available Upon Request

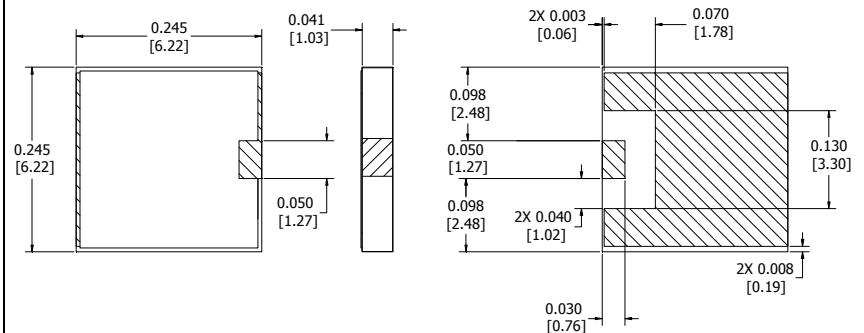
### 5.0 PART NUMBERING

Part Identifier:	SMT252503ALN2F
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## POWER RATING AND DERATING



## MECHANICAL OUTLINE



Unless otherwise specified: TOLERANCE: ± .010

\* Note: Specifications are subject to change without notice.

\*\*NOTE: Power handling may vary depending on mounting and heat sinking method.